

70/67/10

| SUE CLASSIFICATION | |
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| Class | Subclass |

PATENT NUMBER

2003-1310

U.S. UTILITY Patent Application

O.I.P.E.

PATENT DATE

12W
SCANNED A.G.1 Q.A. VM

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|------------------------------|-------------------|--------------------------------|-----------------|--------------------------|------------------------|
| APPLICATION NO. 09/761738 | CONT/PRIOR D F | CLASS 118 138 | SUBCLASS 514 | ART UNIT 1763 2524 | EXAMINER Lebentritt |
|------------------------------|-------------------|--------------------------------|-----------------|--------------------------|------------------------|

APPLICANTS

Shigenobu Maeda

TITLE

Manufacturing method of semiconductor wafer, semiconductor manufacturing apparatus, and semiconductor device

PTO-2040
12/99

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ISSUING CLASSIFICATION

[illegible]☐ Continued on Issue Slip Inside File Jacket
TERM
DISC

DRAWINGS

CLAIMS ALLOWED

Sheets Drwg.

Figs. Drwg.

Print Fig.

Total Claims

Print Claim for O.G.

☐ The term of the contract subsequent to the date of the contract has been disclosed.

☐ The term _____
not extend bey
of U.S Patent.

☐ The term of this patent has

NOTICE OF ALLOWANCE MAILED

(Assistant Examiner)

(Date)

ISSUE FEE

Amount Due

Date Paid

(Primary Examiner)

(Date)

ISSUE BATCH NUMBER

(Legal Instruments Examiner)

(Date)

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Form **PTO-436A**
(Rev. 6/99)

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(FACE)

2003-1310